

# SIIQ DIRECT Business Meeting 2010 & MAP 2010 Program Overview

| Wednesday 17 <sup>th</sup> November, 2010                               |   |                             |
|---|---|-----------------------------|
| Time  | Presentation @Argos C   | Exhibition @Argos A & B     |
| 13:00 ~ 13:05   | Opening Remark  | Poster<br>&<br>Exhibition * |
| 13:05 ~ 14:35   | Session 1: Invited Talks *  |                             |
| 14:35 ~ 15:00   | Coffee Break  |                             |
| 15:00 ~ 17:10   | Session 2: 3D Integration Process Technology *  |                             |
| 17:10 ~ 17:30   | Coffee Break  |                             |
| 17:30 ~ 18:00   | Session 3: ASTSA-MOU Session  |                             |
| 18:15 ~ 19:30   | Reception Party @Tinga Tinga (5F)   |                             |
| Thursday 18 <sup>th</sup> November, 2010                                |   |                             |
| 09:00 ~ 10:40   | Session 4: Sensor and its Application *<br>Regional Innovation Cluster Program 【Global Type(2nd Stage)<br>Expansion Program Workshop】 | Poster<br>&<br>Exhibition * |
| 10:40 ~ 11:00   | Coffee Break  |                             |
| 11:00 ~ 12:15   | Session 5: 3D Integration Consortium *<br>Regional Innovation Cluster Program 【Global Type(2nd Stage)<br>Expansion Program Workshop】  |                             |
| 12:15 ~ 13:00   | Lunch Break   |                             |
| 13:00 ~ 15:20   | Session 6: Green Device *   |                             |
| 15:20 ~ 15:50   | Coffee Break  |                             |
| 15:50 ~ 17:40   | Session 7: Assembling and Analysis *  |                             |
| 17:40 ~ 18:00   | Coffee Break  |                             |
| 18:00 ~ 18:40   | Session 8: India Session *  |                             |
| 18:45 ~ 19:45   | Session 9: Poster Session with Wines @Argos A & B   |                             |
| Friday 19 <sup>th</sup> November, 2010: Excursion in FUKUOKA & NAGASAKI |   |                             |
| 09:30 ~ 10:30   | Hydrogen Energy Test and Research Center (HyTReC)   |                             |
| 10:30 ~ 11:00   | Center of System Integration Platform Organization Standards (CSIPOS)   |                             |
| 14:00 ~ 15:00   | Mitsubishi Heavy Industries, Ltd. Nagasaki Shipyard & Machinery Works, Isahaya Plant  |                             |

\*Supported by Organization for Small & Medium Enterprises and Regional Innovation, JAPAN (SMRJ)

# SIIQ DIRECT Business Meeting 2010 & MAP2010 Program

Wednesday 17<sup>th</sup>, November

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## 13:00 ~ 13:05 Opening Remark

Chair: Hajime Tomokage

*Fukuoka University (JAPAN)*

## 13:05 ~ 14:35 Session 1: Invited Talks \*

Chair: Todd Takaki

*Inoueki., Ltd. (MALAYSIA)*

- 13:05-13:35 1-1 Potential of Mobility in Robot Business  
Dai Akimoto  
*Segway Japan, Ltd. (JAPAN)*
- 13:35-14:05 1-2 Future of Taiwan Semiconductor Industry  
Stephen Su  
*Industrial Technology Research Institute (ITRI) (TAIWAN)*
- 14:05-14:35 1-3 Electronic Systems Design & Manufacturing (ESDM) Landscape:  
Vision of India Semiconductor Association  
Vidya Mulky  
*India Semiconductor Association (ISA) (INDIA)*

|                                   |
|-----------------------------------|
| <b>14:35 ~ 15:00 Coffee Break</b> |
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## 15:00-17:10 Session 2: 3D Integration Process Technology \*

Chair: Yangdo Kim

*Pusan National University (KOREA)*

- 15:00-15:30 2-1 Recent Development of Embedded Passive Device Technologies  
Yoshitaka Fukuoka  
*Worldwide Electronic Integrated Substrate Technology Inc. (JAPAN)*
- 15:30-15:50 2-2 Panasonic Plasma Etching Technology for Through Silicon Via Process  
Mitsuru Hiroshima  
*Panasonic Factory Solutions Co., Ltd. (JAPAN)*
- 15:50-16:10 2-3 Evaluation of Current Mode and Additives in Copper Via Filling  
Myoung-Won and Jae-Ho Lee  
*Hongik University (KOREA)*
- 16:10-16:30 2-4 Forming Via Holes for Through Silicon Via (TSV) Process using Bosch Process  
Naoyuki Kuratomi  
*SAMCO Inc. (JAPAN)*

- 16:30-16:50 2-5 Low-Temperature and Low-Stress Micro-joining using Compliant Bump for Heterogeneous Integration  
Naoya Watanabe\*\* and Tanemasa Asano\*\*\*  
\*\**Fukuoka Industry, Science & Technology Foundation (Fukuoka IST) (JAPAN)*  
\*\*\**Kyushu University (JAPAN)*
- 16:50-17:10 2-6 Achievement and Future Challenges in 3D Researches  
Hirofumi Nakajima  
*Renesas Electronics Corporation. (JAPAN)*  
*Japan Electronics and Information Technology Association (JEITA) (JAPAN)*  
*Japan Jisso Technology Roadmap Council (JJTRC) (JAPAN)*

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| <b>17:10 ~ 17:30 Coffee Break</b> |
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**17:30 ~ 18:00 Session 3: ASTSA-MOU Session**

Chair: Hajime Tomokage

*Asia Semiconductor Trading Support Association (ASTSA) (JAPAN)*

Panelist 1 Zhihua Wang

*Beijing Semiconductor Industry Association (BSIA) (CHINA)*

Panelist 2 Jae-Ho Lee

*IMAPS —KOREA (KOREA)*

Panelist 3 Vidya Mulky

*India Semiconductor Association (ISA) (INDIA)*

Panelist 4 Joseph Fjelstad

*Microelectronics Packaging and Test Engineering Council (MEPTEC) (U.S.A.)*

Panelist 5 Zabidi Mahbar

*Malaysian Industrial Development Authority (MIDA) (MALAYSIA)*

**18:15 ~ 19:30 Reception Party @Tinga Tinga (5F)**

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**Thursday 18<sup>th</sup>, November**

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**09:00-10:40 Session 4: Sensor and its Application \***

**Regional Innovation Cluster Program 【Global Type(2nd Stage) Expansion Program Workshop】**

Chair: Eddie Ohtsuru

*Fukuoka Industry, Science & Technology Foundation (Fukuoka IST) (JAPAN)*

09:00-09:25 4-1 Nanotechnology for Detection and Prognosis of Disease Stage: Protein Quantification for Clinical Approach

Min-Ho Lee

*Korea Electronics Technology Institute (KETI) (KOREA)*

09:25-09:50 4-2 Development of Technologies Based on Social Needs

Ashir Ahmed

*Kyushu University (JAPAN)*

- 09:50-10:15 4-3 Reflow Type Voice Coil Motor for Auto Focus Camera Module  
Sherman Yip  
*AAC Acoustic Technologies Holdings Inc. (CHINA)*
- 10:15-10:40 4-4 Status, Trends and Opportunities of Technologies for Integrated Circuit Design in Mainland China  
Zhihua Wang  
*Tsinghua University (CHINA)*  
*Beijing Semiconductor Industry Association (BSIA) (CHINA)*

|                                   |
|-----------------------------------|
| <b>10:40 ~ 11:00 Coffee Break</b> |
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**11:00 ~ 12:15 Session 5: 3D Integration Consortium \***

**Regional Innovation Cluster Program 【Global Type(2nd Stage) Expansion Program Workshop】**

Chair: Akihiro Kawaguchi

*Fukuoka Industry, Science & Technology Foundation (Fukuoka IST) (JAPAN)*

- 11:00-11:25 5-1 3D IC Packaging and its Challenges  
Carl Chen  
*Siliconware Precision Ind. Co., Ltd. (SPIL) (TAIWAN)*
- 11:25-11:50 5-2 The IC Industry of Vietnam ~ A Quick Overview and Prospective Development~  
Dang Luong Mo  
*Vietnam National University (VIETNAM)*
- 11:50-12:15 5-3 Fukuoka Institute of Advanced Semiconductor Packaging & Assembling Research  
Shun-ichi Hiraki  
*Fukuoka Industry, Science & Technology Foundation (Fukuoka IST) (JAPAN)*

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| <b>12:15 ~ 13:00 Lunch Break</b> |
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**13:00 ~ 15:20 Session 6: Green Device \***

Chair: Masahiro Kashiwagi

*Kumamoto Industrial Research Institute. (JAPAN)*

- 13:00-13:20 6-1 Trends of Photovoltaic (PV) Solar Industry and Technology  
Donghwan Kim  
*Korea University (KOREA)*
- 13:20-13:40 6-2 Silicon: The Promise of Power  
Saji Salkalachen  
*Bharat Heavy Electricals Limited. (INDIA)*
- 13:40-14:00 6-3 Low-Power Testing for Low-Power Devices  
Xiaoqing Wen  
*Kyushu Institute of Technology (JAPAN)*
- 14:00-14:20 6-4 Ultra-low On-resistance LDMOS Implementation in 0.13 $\mu$ m CD and BiCD Process Technologies for Analog Power IC's  
Koji Kimura  
*Toshiba Corporation Semiconductor Company (JAPAN)*

- 14:20-14:40 6-5 Emerging Trends in Electric Mobility – A Global Perspective  
P. Bala  
*Auxineon Pte. Ltd. (INDIA)*
- 14:40-15:00 6-6 Investment Opportunities in the Electronic and Solar Industries in Malaysia  
Zabidi Mahbar  
*Malaysian Industrial Development Authority (MIDA) (MALAYSIA)*
- 15:00-15:20 6-7 ECU Design for Automotive Systems as per ISO 26262  
Sathyaraja H Nandugudi  
*Patni Computer Systems Ltd. (INDIA)*

**15:20 ~ 15:50 Coffee Break**

**15:50 ~ 17:40 Session 7: Assembling and Analysis \***

Chair: Seiichiro Yoshida

*New Japan Radio Co., Ltd. (JAPAN)*

- 15:50-16:20 7-1 Copper Wire-Bonding for Fine Pitch Interconnections  
Shoji Uegaki  
*ASE Marketing & Service Japan Co., Ltd. (JAPAN)*  
*Microelectronics Packaging and Test Engineering Council (MEPTEC) (U.S.A.)*
- 16:20-16:40 7-2 Brilliant Jafeng  
Yunfeng Wang  
*Dalian Jafeng Electronics Co., Ltd. (CHINA)*
- 16:40-17:00 7-3 Thermal Defect Localization Technique Using ELITE (Enhanced Lock in Thermal Emission)  
Randy Schussler  
*DCG Systems, Inc. (U.S.A.)*
- 17:00-17:20 7-4 Current and Potential Future Trends for Electronic Assembly  
Joseph Fjelstad  
*Verdant Electronics (U.S.A.)*
- 17:20-17:40 7-5 Emerging Embedded Devices into Substrate for More than Moore Era  
Henry H. Utsunomiya  
*Interconnection Technologies, Inc. (JAPAN)*  
*Japan Electronics and Information Technology Association (JEITA) (JAPAN)*

**17:40 ~ 18:00 Coffee Break**

**18:00 ~ 18:40 Session 8: India Session \***

Chair: Daisuke Yamaguchi

*Keirex Technology Inc. (JAPAN)*

- 18:00-18:20 8-1 Reducing Photomask Cost through Innovative Mask Data Preparation and Defect Analysis  
Software  
Nachiket Urdhwareshe  
*SoftJin Technologies Pvt. Ltd. (INDIA)*

18:20-18:40 8-2 Innovation in Software & Systems Domain in India  
Anil Gupta  
*Metalogic Circuits India Pvt. Ltd. (INDIA)*

**18:45 ~ 19:45 Session 9: Poster Session with Wines @Argos A & B**

Chair: KS Dorai Arasu

*InfoSree Technologies Pvt. Ltd. (INDIA)*

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**Friday 19<sup>th</sup>, November**

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**09:00 ~ 17:30 Excursion**

09:00 ~ 1F Robby, Hilton Fukuoka Sea Hawk  
09:30 ~ 10:30 Hydrogen Energy Test and Research Center (HyTReC)  
10:30 ~ 11:00 Center of System Integration Platform Organization Standards (CSIPOS)  
11:30 ~ 12:30 Lunch  
14:00 ~ 15:00 Mitsubishi Heavy Industries, Ltd. Nagasaki Shipyard & Machinery Works, Isahaya Plant  
~ 18:30 Fukuoka Airport, Hakata Station & Hilton Fukuoka Sea Hawk

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**Wednesday-Friday 17<sup>th</sup> -18<sup>th</sup>, November**

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**Exhibition @ARGOS A & B**

|   |   |
|---|---|
| Advantest Corporation (JAPAN) *                             | ALPHA DESIGN Co., Ltd. (JAPAN)                          |
| Auxineon PTE LTD. (INDIA) *                                 | BEAMSENSE Co., Ltd. (JAPAN)                             |
| Bharat Heavy Electricals Ltd. (INDIA) *                     | Chiyoda Trading Corporation (JAPAN)                     |
| Dalian Jafeng Electronics Co., Ltd. (CHINA) *               | DCG Systems K.K. (JAPAN)                                |
| DENKEN CO., Ltd. (JAPAN) *                                  | Disco Corporation (JAPAN)                               |
| ELLA Co., Ltd. (JAPAN) *                                    | Espec Kyushu Corp. (JAPAN) *                            |
| Fuji Machine Mfg. Co., Ltd. (JAPAN)                         | FUKUDEN SHIZAI Co., Ltd. (JAPAN) *                      |
| Fukuoka Industry, Science & Technology Foundation (JAPAN) * | Fukuoka University/FIST (JAPAN) *                       |
| Hirai Seimitsu Kogyo Corporation (JAPAN) *                  | Hongik University (KOREA) *                             |
| India Semiconductor Association (INDIA) *                   | Industrial Technology Research Institute (TAIWAN) *     |
| INOUEKI Co., Ltd. (JAPAN) *                                 | Iwatsu Test Instruments Corporation (JAPAN)             |
| JR Kyushu Patni Sysytems, Inc. (JAPAN)                      | KASHIMA ELECTRONICS INC. (JAPAN) *                      |
| Korea University (KOREA) *                                  | Kyushu Institute of Technology (JAPAN)/FIST (JAPAN) *   |
| Kyushu University (JAPAN)/FIST (JAPAN) *                    | Malaysian Industrial Development Authority (MALAYSIA) * |
| Marubun Corp. (JAPAN)                                       | Metalogic Circuits (I) Pvt., Ltd. (INDIA) *             |
| Mitsuboshi Diamond Industrial Co., Ltd. (JAPAN)             | Nikon Tec Corporation (JAPAN)                           |
| SAMCO Inc. (JAPAN)  | Segway Japan, Ltd. (JAPAN)                              |
| Senju Metal Industry Co., Ltd. (JAPAN) *                    | Shintec Co., Ltd. (JAPAN) *                             |
| Silicon Artist Technology Co., Ltd. (JAPAN) *               | Siliconware Precision Ind. Co., Ltd. (TAIWAN) *         |
| SoftJin Technologies Pvt. Ltd. (INDIA) *                    | TAIKO REFRACTORIES Co., Ltd. (JAPAN)                    |
| Tokuyama Corporation (JAPAN)                                | Tsinghua University (CHINA) *                           |
| Vietnam National University (VIETNAM)/FIST (JAPAN) *        | Wabo Electronics Co., Ltd. (JAPAN) *                    |
| WALTS Co., Ltd. (JAPAN) *                                   | Yashima Sangyo Co., Ltd. (JAPAN)                        |
| Yukawa Crown Co., Ltd (JAPAN) *                             |   |

(47 Posters, Alphabet Order)